

薄ウエハー厚み測定機

Thickness Measuring Device for Thin Wafer

Model: Real BG300



MICRO GRANITE®

All the sensors carried in MICRO GRANITE equipment are standard goods marketed.

If you specify the characteristics to be inspected and the sensor which a customer needs, it will include in MICRO GRANITE equipment (XYZ and turn axis) and a program will be manufactured.

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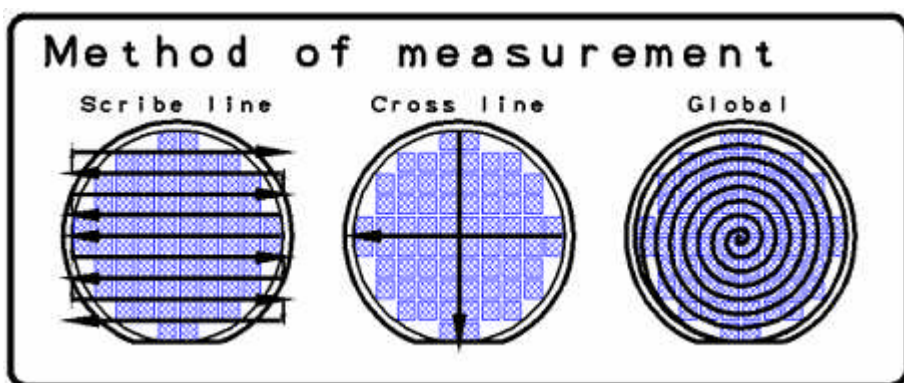
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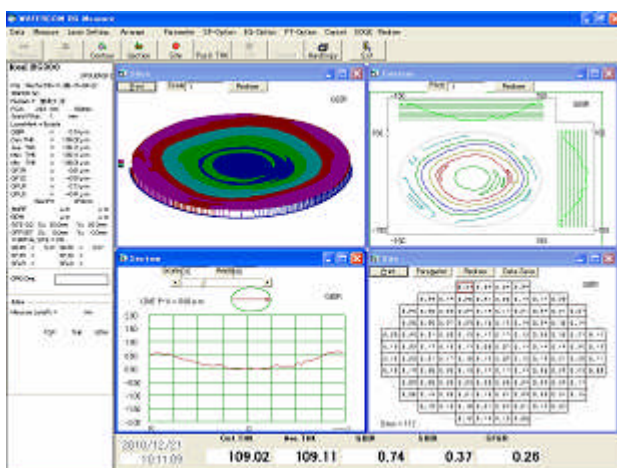
<http://www.micro-granite.co.jp>

Real BG300は、バックグラインド工程後の多機能な厚み計測装置です。
 シリコン透過式変位センサーを用いてシリコンウェハー厚みを非接触で検出します。
 高精度なX軸（左右軸）、Y軸（前後軸）とθ軸（回転軸）を有し、XYθ軸にて2本の中心ライン測定、切断されるチップ間のスクライブライン測定。また、Y軸とθ軸にてスパイラル軌道による全面の厚み測定も可能です。
 透過式変位センサーを使用している為、バックグラインドフレーム付きウエハ・保護膜付きウエハも測定出来ます。
 注）本機、厚み測定にはウエハ表面粗さ約#2000メツシュ以上の鏡面が必要です。

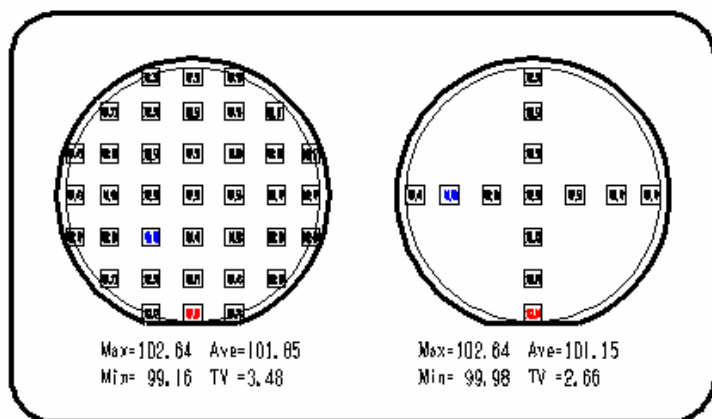
The **Real BG300** model is a post-back grind processing multifunctional thickness measuring device.
 It uses silicon transmission displacement sensors to detect the thickness of silicon wafers without making contact.
 Taking high-precision X-axis (left-right axis), Y-axis (forward-back axis), and θ-axis (rotational axis) readings, it measures 2 central lines on the X-, Y-, and θ-axes, as well as measuring scribe lines cut between chips. It is also capable of measuring the thickness of the entire surface on the Y-axis and θ-axis using spiral vectors.
 Since it employs silicon transmission displacement sensors, the **Real BG300** can also measure wafers with affixed back grind frames or protective film(back grind tape).
 Please note: To measure thickness, this device requires a mirrored surface with wafer surface roughness of around #2000 mesh or greater.



Scanning method



Example of Analysis 1



Example of Analysis 2

仕様 Specifications		
ウエハーサイズ	Wafer Diameter	200/300mm
検出器	Sensor	CHR-IT
分解能	Resolution	0.2 μm
検出範囲	Range	40~3500 μm
繰り返し精度	Resolution	0.2 μm
対称表面	Surface	鏡面のみ(only polished surface)
定義	Parameter	GBIR/D GFLR/D GF3R/D SBIR/D TV5 TV9 TV17,Muti-points
空気源	Air Pressure	0.4Mpa Dry Air
電源	Power	AC110V
装置の大きさ	Dimensions	450(W)×600(D)×1400(H)mm
重量	Weight	150kg